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Function | Sheet Number
--- | ---
01-Cover | 01
02-ALI3 Adaptor Board | 02

Revision / History
V0: Draft version for internal review
V1: Revise components
Mated PCB V1
V2: Revise components
Made PCB wider, changed PN from HKADS-13-02-08W-0100 to BD-ALI3-SHARP3-G

7/8/2014
Suggested Stack Up

1.4mil | 5mil | L1 TOP LAYER | 0.5oz Cu + 0.5oz Plate
0.7mil | 5mil | L2 GND | 0.5oz Cu
0.7mil | 5mil | L3 PWR | 0.5oz Cu
1.4mil | 5mil | L4 BOTTOM LAYER | 0.5oz Cu + 0.5oz Plate

Impedance Control | Trace Width/Space | Impedance
--- | --- | ---
Differential | 4.5 / 7 / 4.5 (mil) | 100 ohm 5%
Single Ended | 5 (mil) | 50 ohm 10%

* Manufacturer should change the stack up to match the impedance control base on the PCB material used.

ALI3-SHARP7-PCB-A HKADS-13-02-HW-0100
Ref Sch: V2 7/8/2014 1:31:12 PM
Board Thickness: 1.6mm 4 Layers FR4

Top Layer | Top Overlay
--- | ---
Keep-Out Layer
Mechanical 1 | Mechanical 5

Board shall be fabricate - Performance Class II as per IPC-6011 & IPC-6012
Material: Per IPC-4101A/24/26/29/99, Copper Clad,
High Temperature FR4 Class Epoxy Glass Rated UL94V-0,
0.5 OZ Copper for External Layers & 0.5 OZ Copper for Internal Layers.
Must be RoHS compliant & survive a Lead-Free Assembly Max reflow of 260 DEG C (6 Passes)
Td Rating: >340 DEG C
Z Axis CTE < 3.5%
Tg > 170 DEG C (Min)

Solder Mask: SMOBC Per IPC-SM-840C, Class T, Must be RoHS Compliant
TYP LPI, 0.0002 Min to 0.0008 Max measured over copper plating,
must clear all lands as indicated on gerber solder mask layers, (Color = Red)

Finish: Electro-less Nickel Immersion Gold (ENIG), 2"8 Micro Inches Gold Over 150°250 Micro Inches Nickel
This Assembly shall be RoHS Compliant. Vendor shall deliver assembly with accompanying certificate of compliance.